



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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The MS Series of thermoelectric modules (TEMs) are designed to reach cool down temperatures that are not achievable with single stage TEMs.



This product line is available in numerous heat pumping capacities, geometric shapes and temperature differentials. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the MS Series is designed for higher current and lower heat-pumping applications.

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FEATURES

- High temperature differential
- Precise temperature control
- Reliable solid state operation
- Environmentally friendly
- DC operation
- RoHS compliant

APPLICATIONS

- CCD cameras
- Electron microscope
- Calibration equipment
- Photonics laser systems
- Gas analyzers
- Infrared (IR) sensors
- Guidance systems

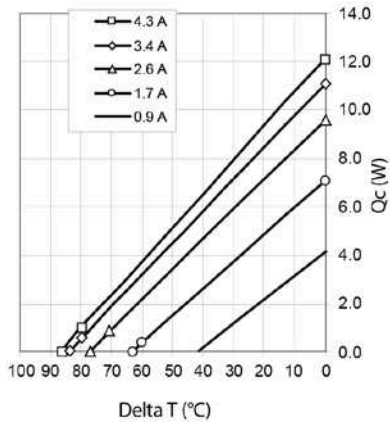
SPECIFICATIONS

PERFORMANCE	
Hot Side Temperature (°C)	25°C
Qmax (Watts)	12.1
Delta Tmax (°C)	87
I _{max} (Amps)	4.3
V _{max} (Volts)	8.2

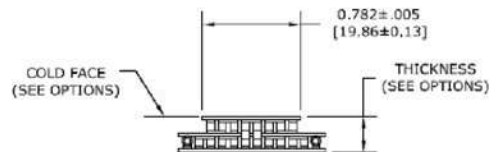
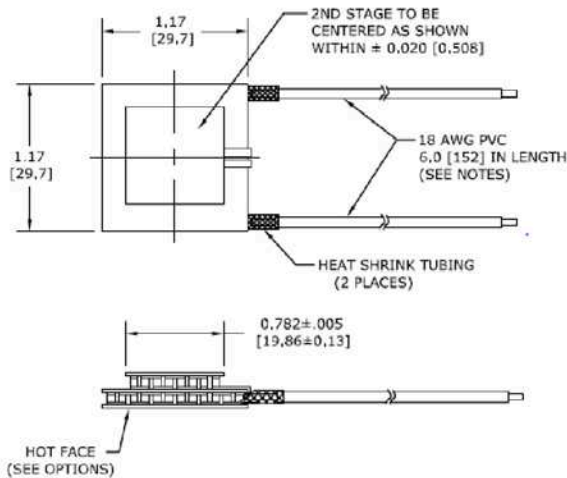
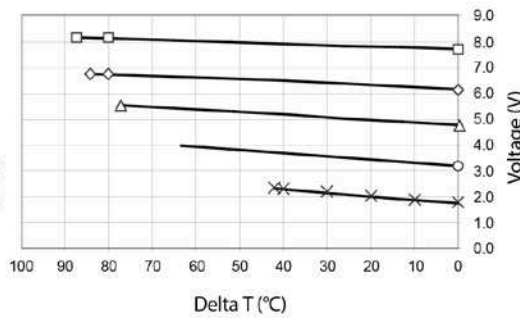
SUFFIX	THICKNESS PRIOR TO TINNING	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
00	0.296" ± 0.015"	0.015" / 0.015"	Metallized	Metallized	6.0"
11	0.288" ± 0.015"	0.015" / 0.015"	Lapped	Lapped	6.0"
22	0.296" ± 0.015"	0.015" / 0.015"	Pre-tinned	Pre-tinned	6.0"

Performance Curves at Th = 25°C

THERMO



ELECTRIC



Ceramic Material: 100% (Al₂O₃)
 Solder Construction: 138°C, Bismuth Tin (BiSn)

OPERATING TIPS

- Max operating temperature: 80°C
- Do not exceed I_{max} or V_{max} when operating module
- Reference assembly guidelines for recommended installation
- Solder tinning also available on metallized ceramics

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